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(54) Title: EMBEDDED VERTICAL INDUCTOR IN LAMINATE STACKED SUBSTRATES

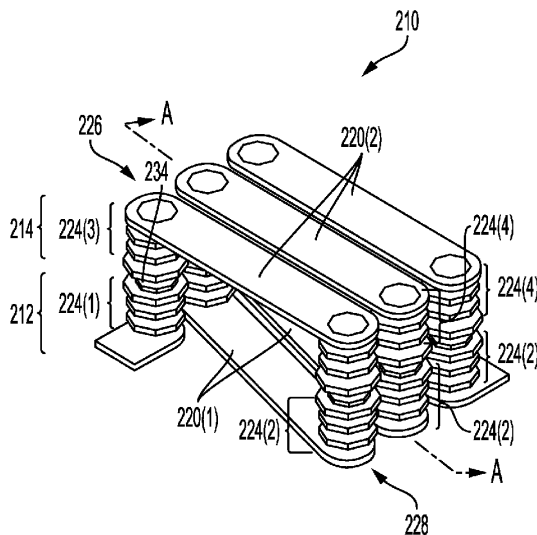


FIG. 2A

(57) Abstract: A vertical inductor structure includes a first laminate substrate forming a first portion of the vertical inductor structure and a second laminate substrate forming a second portion. Each laminate substrate includes a plurality of first traces embedded in a layer of the laminate substrate, a plurality of first vertical columns, and a plurality of second vertical columns. Each first vertical column is coupled to a first end of a respective first trace, and each second vertical column is coupled to a second end of a respective first trace. The second laminate substrate is mounted on the first laminate substrate such that each first vertical column of the first laminate substrate is coupled to a respective first vertical column of the second laminate substrate, and each second vertical column of the first laminate substrate is coupled to a respective second vertical column of the second laminate substrate.

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